

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.10246	100.0	2.14708
			<b>Subtotal</b>	<b>0.10246</b>	<b>100</b>	<b>2.14708</b>
Die	Doped silicon	Silicon (Si)	7440-21-3	0.29109	100.0	6.1
			<b>Subtotal</b>	<b>0.29109</b>	<b>100</b>	<b>6.1</b>
Solder Wire	Tin alloy	Tin (Sn)	7440-31-5	0.02682	10.0	0.562
	Silver alloy	Silver (Ag)	7440-22-4	0.00536	2.0	0.1124
	Lead alloy	Lead (Pb)	7439-92-1	0.236	88.0	4.9456
			<b>Subtotal</b>	<b>0.26818</b>	<b>100</b>	<b>5.62</b>
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.03688	100.0	0.77295
			<b>Subtotal</b>	<b>0.03688</b>	<b>100</b>	<b>0.77295</b>
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.00701	0.03	0.14694
	Pure metal layer	Zinc (Zn)	7440-66-6	0.00467	0.02	0.09796
	Pure metal layer	Tin (Sn)	7440-31-5	0.00701	0.03	0.14694
	Pure metal layer	Iron (Fe)	7439-89-6	0.02571	0.11	0.53877
	Pure metal layer	Copper (Cu)	7440-50-8	23.32793	99.81	488.8594
			<b>Subtotal</b>	<b>23.37233</b>	<b>100</b>	<b>489.79001</b>
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.24656	100.0	5.167
			<b>Subtotal</b>	<b>0.24656</b>	<b>100</b>	<b>5.167</b>
Mould Compound	Polymer	Tetrabromobisphenol A/Epichlorohydrin polymer	40039-93-8	2.27047	3.0	47.58
	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	4.54095	6.0	95.16
	Polymer	Epichlorohydrin/o-Cresol/Formaldehyde polymer (generic)	29690-82-2	7.56825	10.0	158.6
	Carbon Black	Carbon black	1333-86-4	0.37841	0.5	7.93
	Filler	Misc. Silica compounds (generic)	14808-60-7	59.03234	78.0	1237.08
	Flame retardant	Antimony Trioxide (Sb2O3) - cas no. 1309-64-4	1309-64-4	1.89206	2.5	39.65
			<b>Subtotal</b>	<b>75.68248</b>	<b>100</b>	<b>1586</b>
			<b>Total</b>	<b>99.99998</b>	<b>100</b>	<b>2095.59704</b>

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